### e-Manufacturing & Design Collaboration Symposium 2018

## September 7, 2018

#### The Ambassador Hotel HsinChu

## **Sponsor Policy**

This important event benefits your company from three aspects: in-depth exposures to the field engineers of design-houses and chipmakers, direct communications to the supervising managers, and common arena for cross-industry exchanges.

As a Symposium sponsor, you can demonstrate your dedication to manufacturing effectiveness, future factory design and sustainability, get the perfect chance to build company awareness within your target market by providing you with the opportunity to network closely with experts in the industry and bring about win-win results for your company's glory and research promotion.

#### **Sponsor Levels**

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(please note that sponsorship must be			
confirmed prior to the production of each time)			
Sponsor table for distribution company	YES	_	_
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<sup>\*\*</sup> Other sponsorship available, please contact Ms. Celia Shih for detail.

#### **CONTACT INFORMATION**

Ms. Celia Shih

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<sup>\*\*\*</sup>Sign up to be a sponsor now to ensure your company will receive the full benefit of your sponsorship.

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## **Sponsor Application Form**

Sponsor Application Form						
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